

Material Specification

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PROJECT

Design name	: Mobile Charger Reference Design 19.5V / 45W v5		
Board-ID	: TEA1836DB1200	PCB number	: 0000-000-3219-R5-00
Reference	: Patrick van den Hurk	Date	: 20-02-2015
Size single board	: 51.60 x 31.00 mm.	Size panel board	: 103.20 x 155.00 mm.
Size tolerance	: +0.10 -0.20 mm.	Composition	: 2x5, See Panel Drawing
Total layer(s)	: 2	Board thickness	: 0.8 mm. +/- 0.15 mm.
Basic material	: FR4	Board finish	: ENIG
Cu thickness outer layer, finished	: 70 µm.	Cu thickness inner layer	: -- µm.
SMD technologie	: Yes, bottom side only	Powerplanes	: No
Used via type(s)	: Through, Blind, Buried		:
Pasta mask	: Yes, bottom side only	Peel-off mask	: No
Silkscreen	: Yes, both sides	Silkscreen colour	: White
Solder resist	: Yes, both sides	Solder resist colour	: Green

PLOTTER INFORMATION

Units	: Millimeters
Gerber type	: RS274X
Data type	: Absolute X/Y-positive
Output code	: ASCII
Resolution	: 1/10000 mm.

NC DRILL PARAMETERS

Units	: Imperial
Machine	: Excellon
Data format	: 2.3
Output code	: ASCII
Resolution	: 1/10000 inch

NON PLATED THROUGH HOLES

Hole size tolerance, ≤ 0.2 mm.	: +0.05 -0.05 mm.
≥ 0.3 mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

PLATED THROUGH HOLES

Hole size tolerance, ≤ 0.2 mm.	: +0.05 -0.05 mm.
≥ 0.3 mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

MILL BOARD OUTLINES

The position from the boardoutline and boardcutouts represent the exact centerline to complete the dimensions. The milltool has to be positioned near the centerline with a offset half the diameter from the tool.

SCORE BOARD OUTLINES

The position from the boardoutline represent the exact centerline to complete the dimensions. The score tool has to be positioned at the centerline.

BOARD PROPERTIES

Min. isolation outer layer	: 200 µm.	Min. isolation inner layer	: --- µm.
Min. track width outer layer	: 300 µm.	Min. track width inner layer	: --- µm.
Min. hole diameter	: 0.3 mm.		

REMARKS

Manufacturer code allowed.
NXP Logo has to be **filled**.
Milling Through copper allowed.
Singel board has to be panalized, the number of times see panel drawing.
Panel (may) have breakaway edges.
Panel (may) have scoring grooves, both directions.
Add text: 9999-000-32195. This may be done only in the edge.
Create a bottom paste file from the panel. Send this back to customer.

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FILES INCLUDED

Top Paste Mask	: 0000-000-3219-R5-00_SPT.gbx
Top Silkscreen	: 0000-000-3219-R5-00_SST.gbx
Top Solder Resist	: 0000-000-3219-R5-00_SMT.gbx
Top Signal Layer (L1)	: 0000-000-3219-R5-00_TOP.gbx
Bottom Signal Layer (L2)	: 0000-000-3219-R5-00_BOT.gbx
Bottom Solder Resist	: 0000-000-3219-R5-00_SMB.gbx
Bottom Silkscreen	: 0000-000-3219-R5-00_SSB.gbx
Bottom Paste Mask	: 0000-000-3219-R5-00_SPB.gbx
Milling Non Plated	: 0000-000-3219-R5-00_MNP.gbx
Milling Plated	: 0000-000-3219-R5-00_MPL.gbx
NC Drill	: 0000-000-3219-R5-00-1-2.drl
Mechanical Dimensions	: 0000-000-3219-R5-00_DRD.gbx/.pdf
Panel Drawing	: 0000-000-3219-R5-00_PNL.gbx/.pdf
This File	: 0000-000-3219-R5-00_MSP.pdf